



11-26-02

2826

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Cheah *et al.*

Application No.: 10/068,523

Group Art Unit: 2826

Filed: February 5, 2002

Examiner: Alexander O. Williams

For: THERMALLY  
ENHANCED METAL  
CAPPED BGA PACKAGE

Attorney Docket No.: 9818-066-999

#10  
Amend A  
OSmaelskig  
12/22/03

RESPONSE TO THE FIRST OFFICE ACTION

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated August 8, 2002, entry of the following amendments and remarks is respectfully requested.

AMENDMENT

IN THE CLAIMS:

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DEC -3 2002

TECHNOLOGY CENTER 2800

Please cancel claims 2 through 5 without prejudice.

A marked up version of the revised claim, showing insertions and deletions, is included in the Appendix attached hereto.

Please rewrite the pending claims as follows:

1        1. (Amended) A ball-grid array package comprising:  
2              a substrate having first and second sides;  
3              an integrated circuit device attached to said first side of said substrate;  
4              a metal cap having a side wall portion and a top portion forming an internal  
5              cavity, wherein said metal cap is attached to said first side of said substrate along a peripheral